# 2SC4809

### Silicon NPN epitaxial planer type

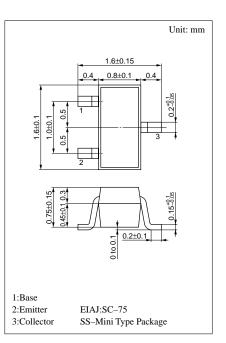
For high-frequency amplification/oscillation/mixing

#### Features

- High transition frequency f<sub>T</sub>.
- Small collector output capacitance C<sub>ob</sub> and common base reverse transfer capacitance C<sub>rb</sub>.
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing.

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Parameter	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	15	V
Collector to emitter voltage	V <sub>CEO</sub>	10	V
Emitter to base voltage	$V_{EBO}$	3	V
Collector current	I <sub>C</sub>	50	mA
Collector power dissipation	P <sub>C</sub>	125	mW
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 ~ +125	°C

#### Absolute Maximum Ratings (Ta=25°C)



Marking symbol : 1S

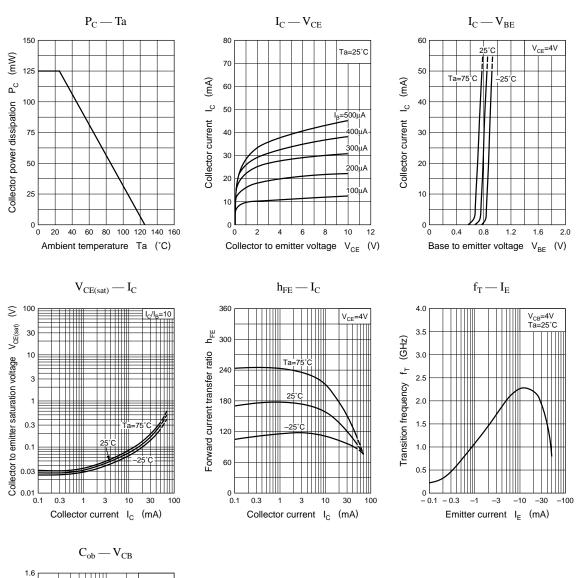
#### Electrical Characteristics (Ta=25°C)

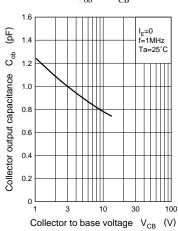
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I <sub>CBO</sub>	$V_{CB} = 10V, I_E = 0$			1	μΑ
Collector to emitter voltage	V <sub>CEO</sub>	$I_C = 2mA$ , $I_B = 0$	10			v
Emitter to base voltage	V <sub>EBO</sub>	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	3			V
Forward current transfer ratio	h <sub>FE</sub> *	$V_{CE} = 4V, I_{C} = 5mA$	75		400	
Collector to emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 20mA$ , $I_B = 4mA$			0.5	V
Transition frequency	f <sub>T</sub>	$V_{CB} = 4V, I_E = -5mA, f = 200MHz$	1.4	1.9	2.7	GHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 4V, I_E = 0, f = 1MHz$		1.4		pF
Base time constant	$r_{bb}' \cdot C_C$	$V_{CB} = 4V, I_E = -5mA, f = 31.9MHz$		11		PS
Common emitter reverse transfer capacitance	C <sub>rb</sub>	$V_{CB} = 4V, I_E = 0, f = 1MHz$		0.45		pF
h <sub>FE</sub> ratio		$\frac{V_{CE} = 4V, I_C = 100\mu A}{V_{CE} = 4V, I_C = 5mA}$	0.75		1.6	

\*hFE Rank classification

Rank	Р	Q	R
h <sub>FE</sub>	75 ~ 130	110 ~ 220	200 ~ 400
Marking Symbol	1SP	1SQ	1SR

### Transistor





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